

P-Channel 20 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|--------------------------------------|---------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}(\Omega)$ | I _D (A) ^c | Q _g (Typ.) | | | |
| - 20 | 0.080 at $V_{GS} = -4.5 \text{ V}$ | - 3.1 | 4.3 nC | | | |
| - 20 | 0.100 at V _{GS} = - 2.5 V | - 2.3 | 4.5110 | | | |

FEATURES

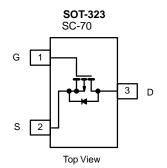
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

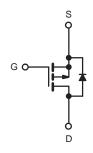


ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Load Switch
- DC/DC Converters





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted) Symbol **Parameter** Limit Unit V_{DS} - 20 Drain-Source Voltage Gate-Source Voltage V_{GS} ± 12 $T_C = 25 \, ^{\circ}C$ - 3.1 $T_C = 70 \, ^{\circ}C$ - 2.1 Continuous Drain Current (T_J = 150 °C) I_D T_A = 25 °C - 1.4^{a, b} T_A = 70 °C - 1.1^{a, b} Α Pulsed Drain Current - 6 I_{DM} $T_C = 25 \, ^{\circ}C$ - 0.4 Continuous Source-Drain Diode Current I_S T_A = 25 °C - 0.3 T_C = 25 °C 0.5 T_C = 70 °C 0.3 P_D Maximum Power Dissipation W T_A = 25 °C 0.4^{a, b} T_A = 70 °C 0.3^{a, b} T_J, T_{stg} - 50 to 150 Operating Junction and Storage Temperature Range °C Soldering Recommendations (Peak Temperature) 260

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Based on $T_C = 25$ °C.



| THERMAL RESISTANCE RATINGS | | | | | | | |
|---|--------------|-------------------|---------|---------|------|--|--|
| Parameter | | Symbol | Typical | Maximum | Unit | | |
| Maximum Junction-to-Ambient ^{a, b} | t ≤ 10 s | R _{thJA} | 250 | 300 | °C/W | | |
| Maximum Junction-to-Foot (Drain) | Steady State | R _{thJF} | 225 | 270 | C/VV | | |

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under steady state conditions is 360 °C/W.

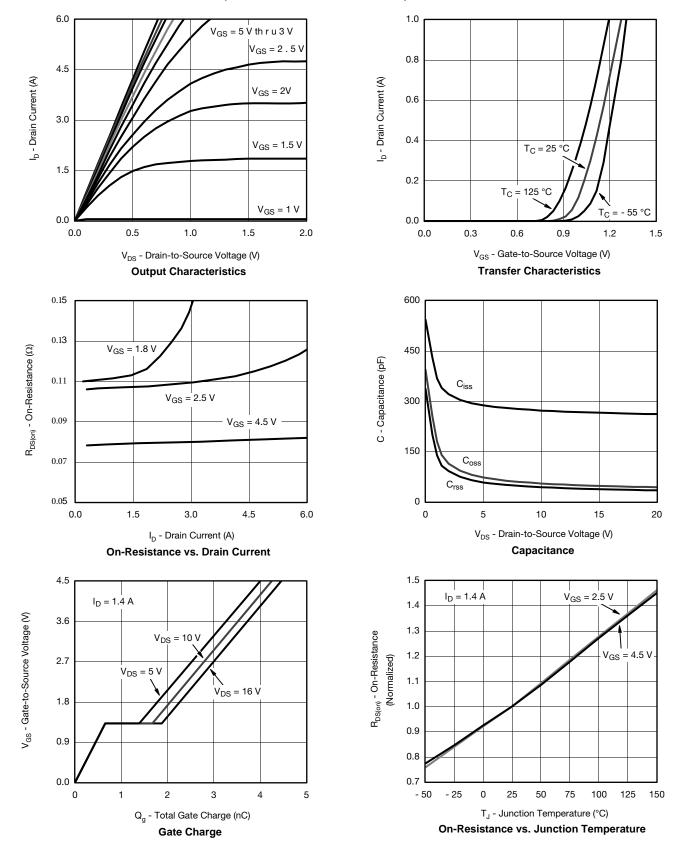
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|---|-------------------------|--|--------|-------|-------|-------|
| Static | | | | I. | I. | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$ | - 20 | | | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I - 250 uA | | - 14 | | mV/°C |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = - 250 μA | | 2.4 | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$ | - 0.45 | | - 1.5 | V |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$ | | | ± 100 | nA |
| Zara Cata Valtaga Praia Current | | V _{DS} = - 20 V, V _{GS} = 0 V | | | - 1 | μA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C | | | - 10 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$ | - 2 | | | Α |
| | | V _{GS} = - 4.5 V, I _D = - 1.4 A | | 0.080 | | Ω |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 2.5 V, I _D = - 1.2 A | | 0.120 | | |
| | ` , | V _{GS} = - 1.8 V, I _D = - 0.3 A | | 0.140 | | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = - 5 V, I _D = - 1.4 A | | 5 | | S |
| Dynamic ^b | | | | | | |
| Input Capacitance | C _{iss} | | | 272 | | pF |
| Output Capacitance | C _{oss} | $V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 55 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 44 | | |
| Total Oats Observe | Q _g | $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.4 \text{ A}$ | | 4.3 | 6.5 | nC |
| Total Gate Charge | | | | 2.7 | 4.1 | |
| Gate-Source Charge | | $V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -1.4 \text{ A}$ | | 0.7 | | |
| Gate-Drain Charge | Q_{gd} | | | 1.0 | | |
| Gate Resistance | R _q | f = 1 MHz | 1.4 | 7 | 14 | Ω |
| Turn-On Delay Time | t _{d(on)} | | | 12 | 20 | ns |
| Rise Time | t _r | $V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$ | | 20 | 30 | |
| Turn-Off DelayTime | t _{d(off)} | $I_{D} \cong -1.1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_{g} = 1 \Omega$ | | 23 | 35 | |
| Fall Time | t _f | | | 9 | 18 | |
| Turn-On Delay Time | t _{d(on)} | | | 5 | 10 | |
| Rise Time | t _r | $V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$ | | 10 | 20 | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \cong -1.1 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$ | | 18 | 27 | |
| Fall Time | t _f | | | 7 | 14 | |
| Drain-Source Body Diode Characterist | • | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | - 2.4 | А |
| Pulse Diode Forward Current ^a | I _{SM} | Ü | | | - 6 | |
| Body Diode Voltage | V _{SD} | I _F = - 0.7 A | | - 0.8 | - 1.2 | V |
| Body Diode Reverse Recovery Time | t _{rr} | · | | 18 | 27 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 7 | 14 | nC |
| Reverse Recovery Fall Time | t _a | $I_F = -0.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | | 7 | | ns |
| Reverse Recovery Rise Time | t _b | 1 | | 11 | | |

Notes:

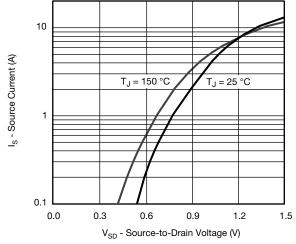
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

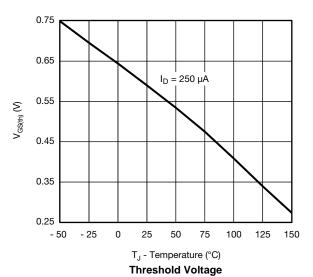


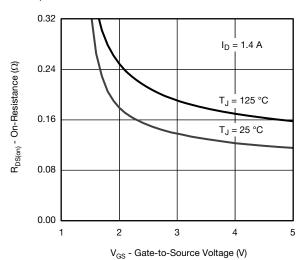




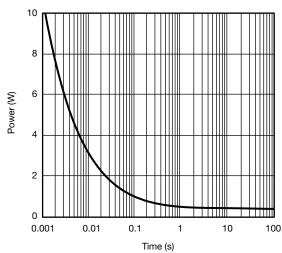


Source-Drain Diode Forward Voltage

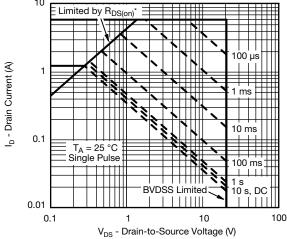




On-Resistance vs. Gate-to-Source Voltage



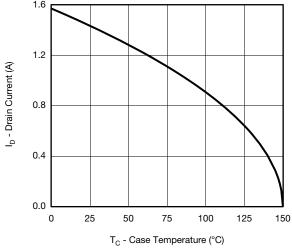
Single Pulse Power, Junction-to-Ambient



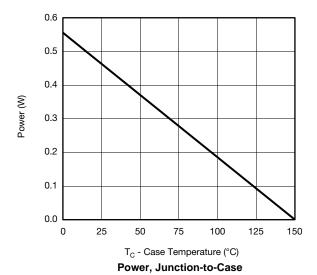
 $^{*}V_{GS}$ > minimum V_{GS} at which $R_{DS(on)}$ is specified

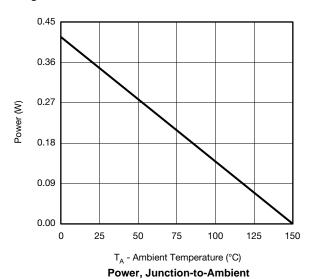
Safe Operating Area, Junction-to-Ambient





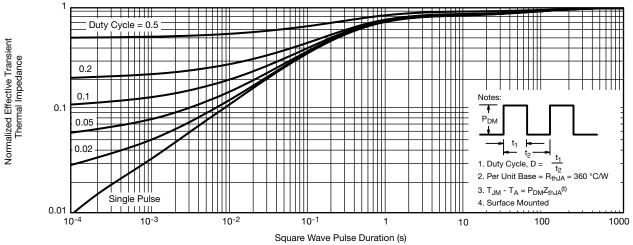
Current Derating*



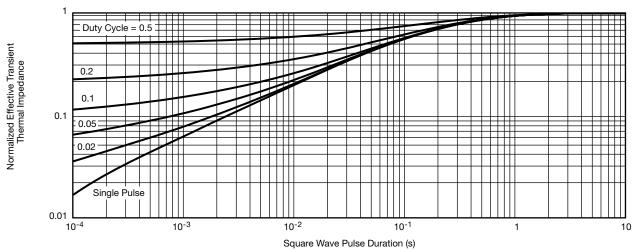


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





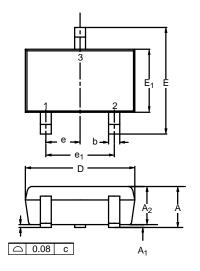
Normalized Thermal Transient Impedance, Junction-to-Ambient

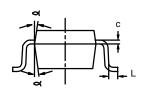


Normalized Thermal Transient Impedance, Junction-to-Foot



SC-70: 3-LEADS

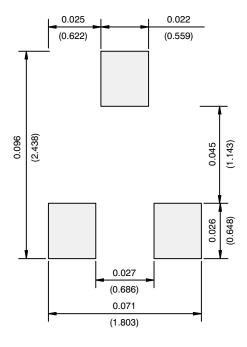




| | MIL | LIMET | METERS INCHES | | | S | |
|---|---------|-------|---------------|----------|-------|-------|--|
| Dim | Min | Nom | Max | Min | Nom | Max | |
| Α | 0.90 | _ | 1.10 | 0.035 | - | 0.043 | |
| A_1 | _ | _ | 0.10 | - | _ | 0.004 | |
| A ₂ | 0.80 | _ | 1.00 | 0.031 | _ | 0.039 | |
| b | 0.25 | _ | 0.40 | 0.010 | _ | 0.016 | |
| С | 0.10 | _ | 0.25 | 0.004 | _ | 0.010 | |
| D | 1.80 | 2.00 | 2.20 | 0.071 | 0.079 | 0.087 | |
| Е | 1.80 | 2.10 | 2.40 | 0.071 | 0.083 | 0.094 | |
| E ₁ | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 | |
| е | 0.65BSC | | | 0.026BSC | | | |
| e ₁ | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 | |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 | |
| 8 | 7°Nom | | | | 7°Nom | | |
| ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549 | | | | | | | |



RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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